



M T B F (E I A J R C R - 9 1 0 2 B)

				Model	SNDBS400B12
No.	Parts		Q' ty of Device	Failure rate [10 ⁻⁶ /H]	Reference
1	IC	Linear	1	0.0240	
2	Transistors	NPN/PNP	0	0.0000	
3	Diodes	FR	2	0.0440	
4	Diodes	switching	2	0.0150	
5	Diodes	Zener	0	0.0000	
6	Photoelectron Device	Photo-coupler	1	0.0700	
7	Resistors	Metal Film	11	0.1760	
8	Resistors	Carbon Film	4	0.0640	
9	Resistors	Power Film	0	0.0000	
10	Resistors	Temperature Fuse	0	0.0000	
11	Resistors	variable	1	0.0160	
12	Varistor	Varistor	0	0.0000	
13	Capacitors	Aluminum Electrolytic	3	0.0570	
14	Capacitors	Film	8	0.0672	
15	Capacitors	Ceramic	3	0.0780	
16	Coil	Line Filter	2	0.0009	
17	Coil	Ferrite Beads	2	0.0004	
18	Fuses		1	0.0200	
19	Switch	Toggle	0	0.0000	
20	Connectors	Printed Crcuit Board	13	0.6760	
21	Connection	Hand Solder	21	0.0546	
22	Connection	Flow Solder	378	0.1966	
23	Connection	Screw	15	0.0150	
24	Printed Crcuit Board	Through Hole	1	0.0450	
25	P S 1		1	2.0945	
Total Failure Rate [10 ⁻⁶ /H]				3.7142	

M T B F	[H]	269,000
Ambient Temperature	[°C]	-
Load Factor	[%]	-